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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE BEFORE THE BOARD OF PATENT APPEALS AND INTERFERENCES

Application. No.

: 10/687,288

Confirmation No. :

7538

1st Named Inventor: Wang Yueh

Art Unit

1756

Filed

: 10/15/2003

Examiner

Daborah Chacko Davis

Docket No.

: 42P17301

Customer No.

8791

Mail Stop Appeal Brief-Patents Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

APPEAL BRIEF IN SUPPORT OF APPELLANT'S APPEAL TO THE BOARD OF PATENT APPEALS AND INTERFERENCES

Sir:

This brief is in furtherance of the Notice of Appeal, filed in the above-captioned case on September 28, 2007. Applicants (hereafter "Appellants") hereby submit this Brief (37 C.F.R. § 41.37). The fees required under § 41.20(b)(2), and any required petition for extension of time for filing this brief and fees therefor, are dealt with in the accompanying Transmittal of Appeal Brief. Appellants respectfully request consideration of this appeal by the Board of Patent Appeals and Interferences for allowance of the above-captioned patent application.

An oral hearing is not desired.

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BLAKELY SOKOLOFF TAYLOR & ZAFMAN LLP

TELEPHONE: (408) 720-8300

INTELLECTUAL PROPERTY LAW 1279 OAKMEAD PARKWAY SUNNYVALE, CA 94085-4040

FACSIMILE: (408) 720-8383 **PECEIVED**

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ppli	cation No.: 10/687,288	Filing Date: 10/15/2003
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	Amendment: (pgs)	☐ Issue Fee Transmittel
×	Appeal Brief (_19_pgs)	☐ Notice of Appeal (in duplicate)
	Application:	☐ Petition for:
	(pgs) w/cover & abstract)	☐ Request for Continued Examination (RCE)
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			Filing Date	October 15, 2003
			First Named Inventor	Wang Yueh
			Art Unit	1756
				Daborah Chacko Davis
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FEE TRANSMITTAL for FY 2007 Patent fees are subject to annual revision. Applicant claims small entity status. See 37 CFR 1,27,		Complete if Known		
		Application Number	10/687,288	
		Filing Date	October 15, 2003	
		First Named Inventor	Wang Yueh	
		Examiner Name	Daborah Chacko Davis	
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SUBMITTED BY				Comp	lete (if applicable)
Name (Print/Type) Brent E.	Vecchia	Registration No. (Attorney/Agent)	48,011	Telephone	(408) 720-8300
Signature Klou	t E. Vechie			Date	11/26/07

Based on PTO/SB/17 (02-01) as prodified by Blakely, Bokuloff, Yeylor & Zafmen (w/r) 02/28/2007. SEND TO: Commissioner for Patients, P.O. Box 1450, Alexandria, VA 22313-1450

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Page 14 of this brief bears the practitioner's signature.

I. REAL PARTY IN INTEREST (37 C.F.R. § 41.37(c)(1)(i))

The real party in interest in this appeal is Intel Corporation of 2200 Mission College Boulevard, Santa Clara, California, 95052, to whom the invention is assigned.

II. RELATED APPEALS AND INTERFERENCES (37 C.F.R. § 41.37(c)(1)(ii))

With respect to other appeals or interferences that will directly affect, or be affected by, or have a bearing on the Board's decision in this appeal, to the best of Appellant's knowledge, there are no such appeals or interferences.

III. STATUS OF THE CLAIMS (37 C.F.R. § 41.37(c)(1)(iii))

The status of the claims in this application are:

A. TOTAL NUMBER OF CLAIMS IN APPLICATION

Claims 21-35 are currently pending in the application.

B. STATUS OF ALL THE CLAIMS

- 1. Claims cancelled: 1-20.
- 2. Claims withdrawn from consideration but not cancelled: NONE.
- 3. Claims pending: 21-35.
- 4. Claims allowed: NONE.
- 5. Claims rejected: 21-35.

C. CLAIMS ON APPEAL

Claims 21-35 are on appeal.

IV. <u>STATUS OF AMENDMENTS (37 C.F.R. § 41.37(c)(1)(iv))</u>

A response was not submitted in response to the Final Office Action mailed on June 28, 2007. A response was submitted on 12/27/06 in response to the Office Action mailed 9/27/06. The response included amendments to the claims. The amendments were entered. A copy of all claims on appeal is attached hereto as an appendix of claims.

V. SUMMARY OF CLAIMED SUBJECT MATTER (37 C.F.R. § 41.37(c)(1)(v))

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Independent claim 21 pertains to a method, according to a first embodiment of the invention. See e.g., Fig. 6, paragraphs [0024] through [0028], and original claim 1. The method includes depositing a layer on a substrate. See e.g., block 605 of Fig. 6 and paragraph [0024]. The method also includes depositing a non-chemically amplified photoresist layer upon the layer. See e.g., the first sentence of the Abstract, block 610 of Fig. 6, and paragraph [0025]. The non-chemically amplified photoresist layer having a developer-soluble resin and a photoactive compound. See e.g., the second sentence of the Abstract, paragraph [0019], and original claim 1. The photoactive compound inhibiting solubility of the developer-soluble resin. See e.g. the fourth sentence of the abstract, original claim 1, paragraphs [0003], [0028], and [0031]. The method also includes exposing selected portions of the non-chemically amplified photoresist layer to an extreme ultra-violet light source (see e.g., block 615 of Fig. 1, paragraph [0027]) such that solubility of the selected portions of the non-chemically amplified photoresist layer is promoted (see e.g., paragraph [0027], the fifth sentence of the Abstract, and original claim 1). The method also includes developing the exposed portions of the non-chemically amplified photoresist layer. See e.g., block 620 of Fig. 6 and paragraph [0028].

Independent claim 30 pertains to a non-chemically amplified photoresist, according to a second embodiment of the invention. See e.g., the first sentence of the Abstract, original claim 10, and paragraph [0001]. The non-chemically amplified photoresist includes a resin that is soluble in a developer. See e.g., the second sentence of the Abstract, original claim 10, and paragraph [0019]. The non-chemically amplified photoresist also includes a photoactive compound. See e.g., the second sentence of the Abstract, original claim 10, and paragraph The photoactive compound is distributed within the non-chemically amplified photoresist. See e.g., the third sentence of the Abstract, original claim 10, and paragraphs [0027] and [0029]. The photoactive compound to promote solubility of a selected portion of the non-

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chemically amplified photoresist exposed to an extreme ultra-violet light source and to inhibit solubility of an unexposed portion of the non-chemically amplified photoresist. See e.g., the fourth and fifth sentences of the Abstract, original claim 10, paragraphs [0028] and [0031].

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VI. GROUNDS OF REJECTION TO BE REVIEWED ON APPEAL (37 C.F.R. § 41.37(c)(1)(vi))

- A. Claim 27 is rejected under 35 U.S.C. § 112, first paragraph, as allegedly failing to comply with the written description requirement.
- B. Claims 21-25 and 30-34 are rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 5,759,739 to Takemura et al. (hereinafter <u>Takemura</u>) in view of U.S. Patent Application Publication No. 2005/0074699 by Sun et al. (hereinafter <u>Sun</u>); and
- C. Claims 21, 26, 30 and 35 are rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 5,358,599 to Cathey et al. (hereinafter <u>Cathey</u>) in view of U.S. Patent Application Publication No. 2005/0074699 by Sun et al. (hereinafter <u>Sun</u>).

VII. ARGUMENT (37 C.F.R. § 41.37(c)(1)(vii))

A. REJECTION OF CLAIM 27 UNDER 35 U.S.C. § 112, FIRST PARAGRAPH, AS ALLEGEDLY FAILING TO COMPLY WITH THE WRITTEN DESCRIPTION REQUIREMENT IS BELIEVED TO BE IMPROPER.

GROUP I: CLAIM 27

Claim 27 recites "wherein the non-chemically amplified photoresist layer does not include a photo-acid generator (PAG)". The Examiner has asserted that "there is no disclosure in the specification teaching that the non-chemically amplified generator does not include a photo acid generator (PAG)". See e.g., page 2 of the Final Office Action mailed 9/27/06.

Appellants respectfully disagree. Paragraph [0005] discloses that "For chemically amplified photoresists, the mechanism is different. Instead of PAC, Photoacid generator (PAG) is used." Paragraph [0031] discloses that "Embodiments of the invention provide a non-chemically amplified photoresist (i.e., does not include PAG)".

Accordingly, Appellants respectfully submit that there is sufficient written description for claim 27, and respectfully request that the rejection of claim 27 be overturned.

B. REJECTION OF CLAIMS 21-25 AND 30-34 UNDER 35 U.S.C. § 103(A) AS ALLEGEDLY BEING UNPATENTABLE OVER U.S. PATENT NO. 5,759,739 TO TAKEMURA ET AL. (HEREINAFTER <u>TAKEMURA</u>) IN VIEW OF U.S. PATENT APPLICATION PUBLICATION NO. 2005/0074699 BY SUN ET AL. (HEREINAFTER <u>SUN</u>) IS BELIEVED TO BE IMPROPER

GROUP II: CLAIMS 21-25 AND 30-34

The Examiner has rejected claims 21-25 and 30-34 under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 5,759,739 to Takemura et al. (hereinafter Takemura) in view

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of U.S. Patent Application Publication No. 2005/0074699 by Sun et al. (hereinafter Sun). Appellants respectfully submit that claims 21-25 and 30-34 are allowable over <u>Takemura</u> and <u>Sun</u>.

Claim 21 recites a method comprising:

"depositing a layer on a substrate;

depositing a non-chemically amplified photoresist layer upon the layer, the non-chemically amplified photoresist layer having a developer-soluble resin and a photoactive compound, the photoactive compound inhibiting solubility of the developer-soluble resin;

exposing selected portions of the non-chemically amplified photoresist layer to an extreme ultra-violet light source such that solubility of the selected portions of the non-chemically amplified photoresist layer is promoted; and

developing the exposed portions of the non-chemically amplified photoresist layer".

Accordingly, claim 21 pertains to a method of using a <u>non-chemically amplified</u> photoresist layer that includes a developer-soluble resin and a photoactive compound that inhibits the solubility of the developer-soluble resin. Furthermore, the method includes exposing selected portions of the non-chemically amplified photoresist layer to an extreme ultra-violet light source.

(1) Firstly, on page 3 of the Final Office Action mailed 6/28/07, the Examiner has admitted that "Takemura does not disclose that the photoresist layer is non-chemically amplified".

However, the Examiner has asserted that "Sun, in [0039], discloses that the chemically amplified photoresist layer can be replaced with a non-chemically amplified photoresist layer". See e.g., the bottom of page 3 of the Final Office Action mailed 6/28/07.

Paragraph [0039] of Sun recites:

[0039] The thin photoresist provides a number of important advantages to the photolithographic process. First, there are no outstanding photoresist patterns in the entire process. Dry etch masking is no longer required for the photoresist, making the photoresist more of a photosensitive layer rather than a photoresist. Second, the photoresist layer is so thin that transparency becomes less of a problem. Third, due to the extraordinarily thin photoresist, this invention opens an opportunity to replace the ever troubling chemically amplified photoresist with non-chemically amplified photoresists for the photolithography process of KrF or shorter wavelengths. Fourth, chances for the protective layer and photoresist patterns to collapse are significantly reduced, if not completely eliminated, due to the low aspect ratios and the excellent adhesion of the protective layers to substrates. Fifth, the thinness of the photoresist will inevitably improve the pattern resolution. Sixth, the exposure focus offset has less impact on a thin photoresist than on a thick one. Critical dimension (CD) variation of the protective layer patterns due to different DOF is less significant due to the thin photoresist.

The Examiner appears to have relied upon the statement in paragraph [0039] that "this invention opens an opportunity to replace the ever troubling chemically amplified photoresist with non-chemically amplified photoresists for the photolithography process of KrF or shorter wave-lengths". As understood by Appellants, this statement means that a whole chemically amplified photoresist be replaced with a whole non-chemically amplified photoresist. The Examiner seems to be incorrectly interpreting this statement to mean that the components of the chemically amplified resists discussed in Takemura would be useful as a non-chemically amplified resist composition. However, the section of Sun relied upon does not disclose this.

Accordingly, neither Sun nor Takemura discloses or renders obvious a non-chemically amplified photoresist layer that includes a developer-soluble resin and a photoactive compound that inhibits the solubility of the developer-soluble resin. Furthermore, neither reference teaches or suggests the desirability of such a non-chemically amplified photoresist layer.

(2) Secondly, <u>Takemura</u> should not be combined with <u>Sun</u> since <u>Takemura</u> pertains to chemically amplified photoresist layers and <u>Sun</u> pertains to non-chemically amplified photoresist layers.

Accordingly, for at least one or more of these reasons, claim 21 and its dependent claims are believed to be allowable over <u>Takemura</u> and <u>Sun</u>.

Independent claim 30 and its dependent claims are believed to be allowable for one or more similar reasons.

For at least these reasons, the claims of Group II (claims 21-25 and 30-34) are allowable over <u>Takemura</u> and <u>Sun</u>.

C. REJECTION OF CLAIMS 21, 26, 30 AND 35 UNDER 35 U.S.C. § 103(A) AS ALLEGEDLY BEING UNPATENTABLE OVER U.S. PATENT NO. 5,358,599 TO CATHEY ET AL. (HEREINAFTER <u>CATHEY</u>) IN VIEW OF U.S. PATENT APPLICATION PUBLICATION NO. 2005/0074699 BY SUN ET AL. (HEREINAFTER <u>SUN</u>) IS BELIEVED TO BE IMPROPER

GROUP III: CLAIMS 21, 26, 30 AND 35

Claim 21 recites a method comprising:

"depositing a layer on a substrate;

depositing a non-chemically amplified photoresist layer upon the layer, the non-chemically amplified photoresist layer having a developer-soluble resin and a photoactive compound, the photoactive compound inhibiting solubility of the developer-soluble resin;

exposing selected portions of the non-chemically amplified photoresist layer to an extreme ultra-violet light source such that solubility of the selected portions of the non-chemically amplified photoresist layer is promoted; and

developing the exposed portions of the non-chemically amplified photoresist layer".

(1) Firstly, on page 4 of the Final Office Action mailed 6/28/07, the Examiner has admitted that "Cathey does not disclose that the photoresist layer is non-chemically amplified".

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However, the Examiner has asserted that "Sun, in [0039], discloses that the chemically amplified photoresist layer can be replaced with a non-chemically amplified photoresist layer".

See e.g., the top of page 5 of the Final Office Action mailed 6/28/07.

As discussed above, Appellants submit that paragraph [0039] of <u>Sun</u> means that a whole chemically amplified photoresist be replaced with a whole non-chemically amplified photoresist. There is no disclosure, and it would not be obvious, to use the components of the chemically amplified resists discussed in <u>Cathey</u> in a non-chemically amplified resist composition as discussed in <u>Sun</u>.

Accordingly, neither <u>Sun</u> nor <u>Cathey</u> discloses or renders obvious a non-chemically amplified photoresist layer that includes a developer-soluble resin and a photoactive compound that inhibits the solubility of the developer-soluble resin. Furthermore, neither reference teaches or suggests the desirability of such a non-chemically amplified photoresist layer.

- (2) Secondly, claim 21 recites in part "exposing selected portions of the non-chemically amplified photoresist layer to an extreme ultra-violet light source such that solubility of the selected portions of the non-chemically amplified photoresist layer is promoted". As understood by Appellants, there is no teaching or suggestion that the resists in Cathey would be suitable for an extreme ultra-violet light source.
- (3) Secondly, <u>Cathey</u> should not be combined with <u>Sun</u> since <u>Cathey</u> pertains to chemically amplified photoresist layers and <u>Sun</u> pertains to non-chemically amplified photoresist layers.

Accordingly, for at least one or more of these reasons, claim 21 and its dependent claims are believed to be allowable over <u>Cathey</u> and <u>Sun</u>.

Independent claim 30 and its dependent claims are believed to be allowable for one or more similar reasons.

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For at least these reasons, the claims of Group III (claims 21, 26, 30 and 35) are allowable over <u>Cathey</u> and <u>Sun</u>.

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CONCLUSION

Based on the foregoing, Appellants request that the Board overturn the rejection of all pending claims and hold that all of the claims of the present application are allowable.

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Appellants respectfully petition for an extension of time to respond to the outstanding Office Action pursuant to 37 C.F.R. § 1.136(a) should one be necessary. Please charge our Deposit Account No. 02-2666 to cover the necessary fee under 37 C.F.R. § 1.17 for such an extension.

Please charge any shortages and credit any overpayment to our Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Tel.: (303) 740-1980 (Mountain Time)

1279 Oakmead Parkway Sunnyvale, California 94085-4040

VIII. <u>CLAIMS APPENDIX (37 C.F.R. § 41.37(c)(1)(viii)</u>)

The text of the claims involved in the appeal are:

- 1 20. (Cancelled)
- 21. (Previously Presented) A method comprising:

depositing a layer on a substrate;

depositing a non-chemically amplified photoresist layer upon the layer, the non-chemically amplified photoresist layer having a developer-soluble resin and a photoactive compound, the photoactive compound inhibiting solubility of the developer-soluble resin;

exposing selected portions of the non-chemically amplified photoresist layer to an extreme ultraviolet light source such that solubility of the selected portions of the non-chemically amplified photoresist layer is promoted; and

developing the exposed portions of the non-chemically amplified photoresist layer.

- 22. (Previously Presented) The method of claim 21, wherein the developer-soluble resin comprises a polyhydroxystyrene-based compound.
- 23. (Previously Presented) The method of claim 22, wherein the photoactive compound comprises a phenyl group.
- 24. (Previously Presented) The method of claim 21, wherein the solubility of the selected portions of the non-chemically amplified photoresist layer is promoted by the photoactive compound forming an acid.
- 25. (Previously Presented) The method of claim 24, wherein the acid is a carbonyl acid.

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- 26. (Previously Presented) The method of claim 21, wherein the developer-soluble resin is produced through a free radical polymerization process using a component selected from the group consisting of vinyl acid, vinyl phenol, and vinyl phenol substitutes.
- 27. (Previously Presented) The method of claim 21, wherein the non-chemically amplified photoresist layer does not include a photo-acid generator (PAG).
- 28. (Previously Presented) The method of claim 27, further comprising:

etching portions of the layer underlying the exposed portions of the non-chemically amplified photoresist layer; and

etching a remaining portion of the non-chemically amplified photoresist layer to produce a patterned layer having one or more features, at least one of the features having a critical dimension of approximately 15 nanometers.

- 29. (Previously Presented) The method of claim 28, wherein the at least one feature has a line wide roughness of less than 2 nanometers.
- 30. (Previously Presented) A non-chemically amplified photoresist comprising:

a resin that is soluble in a developer; and

a photoactive compound, the photoactive compound distributed within the non-chemically amplified photoresist, the photoactive compound to promote solubility of a selected portion of the non-chemically amplified photoresist exposed to an extreme ultra-violet light source and to inhibit solubility of an unexposed portion of the non-chemically amplified photoresist.

31. (Previously Presented) The non-chemically amplified photoresist of claim 30, wherein the resin comprises a polyhydroxystyrene-based compound.

32. (Previously Presented) The non-chemically amplified photoresist of claim 30, wherein the solubility of the selected portion of the non-chemically amplified photoresist is promoted by the photoactive compound forming an acid.

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- 33. (Previously Presented) The non-chemically amplified photoresist of claim 32, wherein the photoactive compound comprises a phenyl group.
- 34. (Previously Presented) The non-chemically amplified photoresist of claim 32, wherein the acid is a carbonyl acid.
- 35. (Previously Presented) The non-chemically amplified photoresist of claim 30, wherein the resin is produced through a free radical polymerization process using a component selected from the group consisting of vinyl acid, vinyl phenol, and vinyl phenol substitutes.

IX. EVIDENCE APPENDIX (37 C.F.R. § 41.37(c)(1)(ix))

To the best of Appellant's knowledge, no evidence has been submitted pursuant to 37 CFR Sections 1.130, 1.131, or 1.132.

X. RELATED PROCEEDINGS APPENDIX (37 C.F.R. § 41.37(c)(1)(x))

(To the best of Appellant's knowledge, there are no related appeals or interferences.)